

IN THE CLAIMS:

Please cancel claims 11-20, 28 and 31 without prejudice or disclaimer.

Please amend the claims as follows:

21. (Amended) A surface acoustic wave duplexer having an antenna terminal, a transmitting terminal and a receiving terminal, comprising:
- a transmitting SAW filter coupled between the antenna terminal and the transmitting terminal;
 - a receiving SAW filter coupled between the antenna terminal and the receiving terminal:
 - a common piezoelectric substrate on which both of the transmitting SAW filter and the receiving SAW filter are formed; and
 - a package covering the common piezoelectric substrate, wherein the antenna terminal, the transmitting terminal and the receiving terminal are formed on the package; and
 - a frequency adjusting circuit being coupled between the antenna terminal and the transmitting SAW filter or the receiving SAW filter, wherein the frequency adjusting circuit has a capacitance element.

22. (Amended) A surface acoustic wave duplexer according to claim 21, further comprising:

a branching filter circuit coupled between the frequency adjusting circuit and the transmitting SAW filter or the receiving SAW filter.

27. (Amended) A surface acoustic wave duplexer according to claim 25, wherein the package has a first layer substrate and a second layer substrate, the first layer substrate is disposed on the second layer substrate, and the branching filter circuit is formed on the first layer substrate or the second layer substrate.

29. (Amended) A surface acoustic wave duplexer according to claim 1, wherein the frequency adjusting circuit has an inductance element and a capacitance element.

30. (Amended) A surface acoustic wave duplexer according to claim 27, wherein the frequency adjusting circuit is formed on the common piezoelectric substrate together with the branching filter circuit.

32. (Amended) A surface acoustic wave duplexer according to claim 1, wherein the frequency adjusting circuit is formed on the package.

33. (Amended) A surface acoustic wave duplexer according to claim 21, wherein the package has a first layer substrate and a second layer substrate, the first layer

substrate is disposed on the second layer substrate and the frequency adjusting circuit is formed on the first layer substrate or the second layer substrate.

34. (Amended) A surface acoustic wave duplexer having an antenna terminal, a transmitting terminal and a receiving terminal, comprising:

a SAW filter chip including a transmitting SAW filter connected with the transmitting terminal and a receiving SAW filter connected with the receiving terminal, wherein both the transmitting SAW filter and the receiving SAW filter are formed on one common piezoelectric substrate;

a package covering the one common piezoelectric substrate, wherein the antenna terminal, the transmitting terminal and the receiving terminal are formed on the package; and

a frequency adjusting circuit being coupled between the antenna terminal and the transmitting SAW filter or the receiving SAW filter, wherein the frequency adjusting circuit has a capacitance element.

35. (Amended) A surface acoustic wave duplexer according to claim 34, further comprising:

a branching filter circuit being coupled between the frequency adjusting circuit and the transmitting SAW filter or the receiving SAW filter.

39. (Amended) A surface acoustic wave duplexer according to claim 35, wherein the branching filter circuit is formed on the package.

40. (Amended) A surface acoustic wave duplexer according to claim 35, wherein the package has a first layer substrate and a second layer substrate, the first layer substrate being disposed on the second layer substrate, and the branching filter circuit is formed on the first layer substrate or the second layer substrate.

42. (Amended) A surface acoustic wave duplexer according to claim 34, wherein the frequency adjusting circuit has an inductance element.

43. (Amended) A surface acoustic wave duplexer according to claim 34, wherein the frequency adjusting circuit is formed on the common piezoelectric substrate.

44. (Amended) A surface acoustic wave duplexer according to claim 21, wherein the package has a multi-layer structure.

45. (Amended) A surface acoustic wave duplexer according to claim 34, wherein the frequency adjusting circuit is formed on the package.

46. (Amended) A surface acoustic wave duplexer according to claim 34, wherein the package has a first layer substrate and a second layer substrate, the first layer substrate being disposed on the second layer substrate, and the frequency adjusting circuit is formed on the first layer substrate or the second layer substrate.

Please add the following new claims:

47. (New) A surface acoustic wave duplexer according to claim 21, wherein capacitance element is coupled in series between the antenna terminal and the transmitting SAW filter or the receiving SAW filter.

48. (New) A surface acoustic wave duplexer according to claim 34, wherein the capacitance element is coupled in series between the antenna terminal and the transmitting SAW filter or the receiving SAW filter.

IN THE ABSTRACT:

Please delete the original Abstract and replace it with the revised Abstract of the Disclosure submitted.